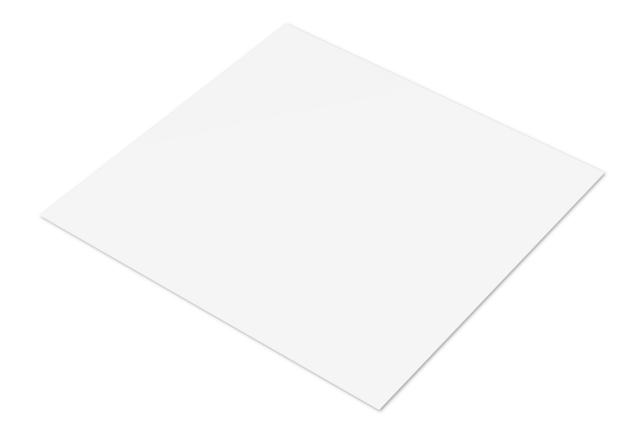


Alphacool Core double sided adhesive thermal pad 100x100x0.25mm

Alphacool article number: 13523





Quick Info

Alphacoot's double-sided adhesive Core thermal pad can be used to cool electronic components of all kinds where it is important to effectively dissipate waste heat. This significantly improves the performance and durability of the components. The assembly is significantly simplified by the material-related tackiness.

- Double sided adhesive for easy mounting
- · Great reliability
- · Great performance
- Customizable

Scope of delivery

1x Alphacool Core double sided adhesive thermal pad 100x100x0.25mm

Technical data

| Dimensions (L x W x H) | 100x100x0.25mm |
|---|-----------------|
| Thermal Conductivity (ASTM D5470) | 1 W/mK ±10% |
| Thickness (ASTM D374) | 0.25 mm |
| Reinforcement Carrier | Fiberglass mesh |
| Continuous Working Temperature | -30~+120 °C |
| Short time use temperature (30sec) | 180 °C |
| Density (ASTM D792) | 1.2 g/cm³ |
| Holding Power 1000g@25° Cusing 1 in² (PSTC-7) | >3000 min |
| 180° Peeling Strength (aluminum) (PSTC-101) | >16 N / 25mm |
| Dielectric Breakdown Voltage (AC) (ASTM D149) | 3 KV ±10% |
| Thermal Impedance @10psi (ASTM D5470) | 1.26 C-in² / W |
| Thermal Impedance @30psi (ASTM D5470) | 1.06 C-in² / W |
| Thermal Impedance @50psi (ASTM D5470) | 1.05 C-in² / W |
| Color | white |

Download links

| Safety data sheets | 13523_Alphacool_Core_double_sided_adhesive_thermal_pad_100x100x0.25mm_SDS(1).pdf 13523_Alphacool_Core_double_sided_adhesive_thermal_pad_100x100x0.25mm_SDS(2).pdf |
|--------------------|---|
| Product pictures | 13523_Alphacool_Core_double_sided_adhesive_thermal_pad_100x100x0.25mm_pics.zip |

Packaging dimensions per unit

| LxWxH | 130 x 130 x 3 mm |
|--------|------------------|
| Weight | 20 g |

Other data

| Certificates | CE, FC, RoHS |
|--------------|---------------|
| EAN | 4250197135238 |
| Customs code | 84733080000 |

Article text

Alphacool's double-sided adhesive Core thermal pad can be used to cool electronic components of all kinds where it is important to effectively dissipate waste heat. This significantly improves the performance and durability of the components. The assembly is significantly simplified by the material-related tackiness.

Flexible and Powerful.

Due to its material composition, the thermal conductive pad is reliable and powerful. With its low thickness, it offers a wide range of application possibilities. It can be flexibly cut to size for individual needs. The adhesive nature allows effortless mounting of electrical components such as DDR modules, motherboard components or power supplies.